

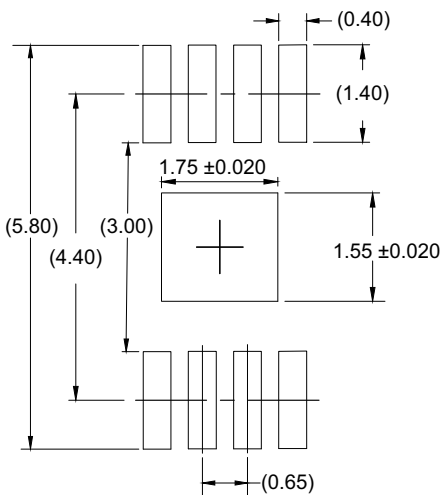
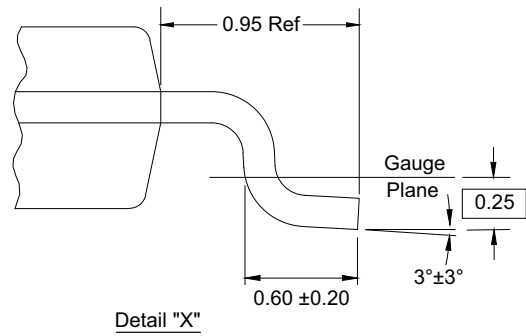
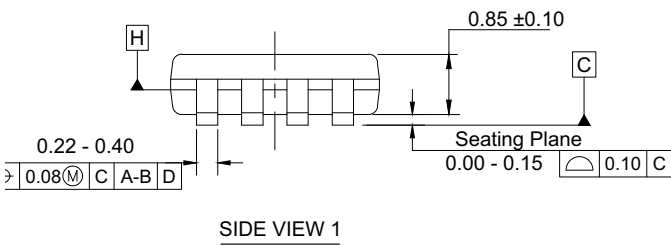
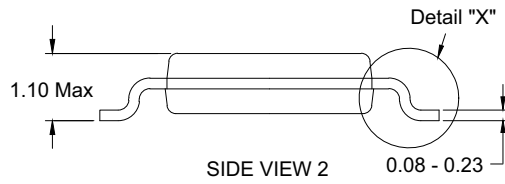
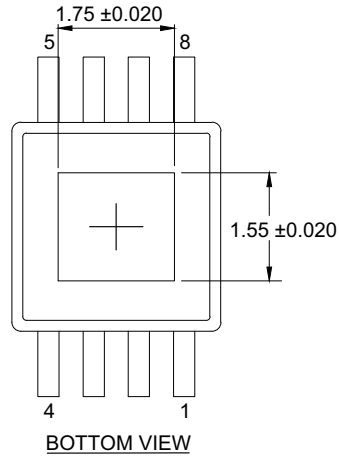
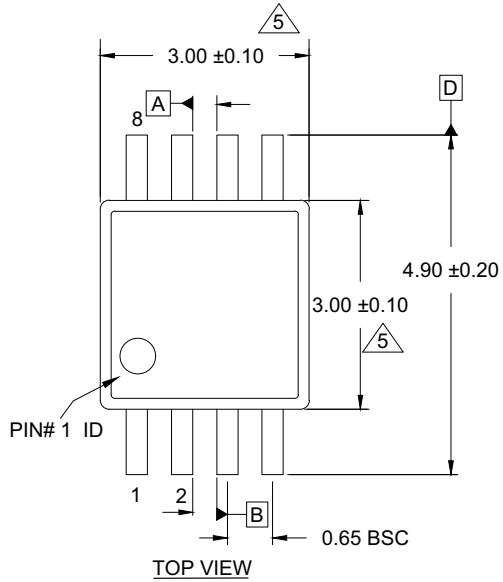
Plastic Packages for Integrated Circuits

Package Outline Drawing

M8.118C

8 Lead Heat-Sink Mini Small Outline Plastic Package (HMSOP)

Rev 0, 9/2023



NOTES:

1. Dimensions are in millimeters.
2. Dimensioning and tolerancing conform to JEDEC MO-187-AA and ASME Y14.5m-1994.
3. Plastic or metal protrusions of 0.15mm max per side are not included.
4. Plastic interlead protrusions of 0.15mm max per side are not included.
5. Dimensions are measured at Datum Plane "H".
6. Dimensions in () are for reference only.